

## **GAS-ASSISTED RAPID THERMAL PROCESSING**

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### **ABSTRACT**

- 5           A system, method and apparatus for processing a semiconductor device including a processing chamber and a heating assembly positioned within the processing chamber. The heating assembly including at least a plate defining an internal cavity configured to receive gas. The gas enters the internal cavity through a first passage at a first temperature, and exits the internal cavity at a
- 10   second temperature through a second passage.